

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph starting at page 9, line 28 as follows:

According to an alternative embodiment of the invention, a thin layer of metal 91 (FIG. 8) is located on the back side of the semiconductor device 12. A layer of adhesive 92 is located between the thin layer of metal 91 and a thicker metal layer 90. The adhesive 92 may extend through the thin layer of metal adhesive 91 to provide adherence to the semiconductor device 12. The thickness of the thin layer of metal 91 layer may be about 0.00254 millimeters. The product shown in FIG. 8 otherwise may be the same as the one shown in FIG. 7.